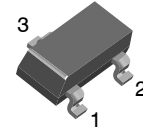


# Small Signal Diode

## BAS35



SOT-23  
CASE 318BM

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage	120	V
I <sub>F(AV)</sub>	Average Rectified Forward Current	200	mA
I <sub>FSM</sub>	Non-Repetitive Peak Forward Surge Current	Pulse Width = 1.0 second	1.0
		Pulse Width = 1.0 microsecond	2.0
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>J</sub>	Operating Junction Temperature	150	°C

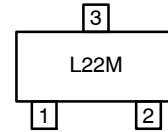
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. These ratings are based on a maximum junction temperature of 150°C.
2. These are steady-state limits. The factory should be consulted on applications involving pulsed or low-duty-cycle operations.

### THERMAL CHARACTERISTICS

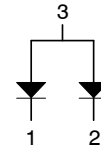
Symbol	Parameter	Ratings	Unit
P <sub>D</sub>	Power Dissipation	350	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	357	

### MARKING DIAGRAM



L22 = Specific Device Code  
M = Date Code

### CONNECTION DIAGRAM



### ORDERING INFORMATION

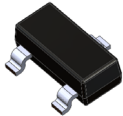
Device	Package	Shipping†
BAS35	SOT-23 3L (Pb-Free, Halide Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

### ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

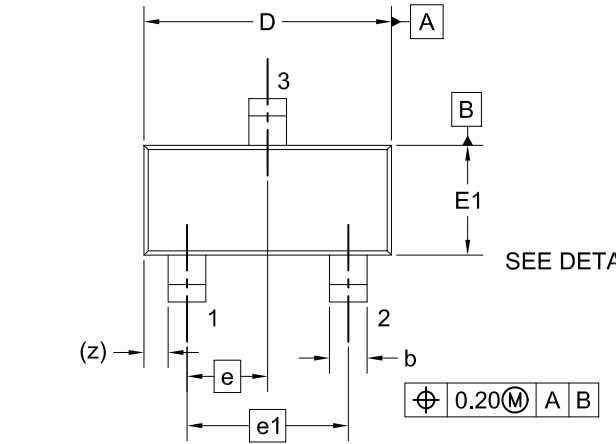
Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>R</sub>	Breakdown Voltage	I <sub>R</sub> = 1.0 mA	120	-	V
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 10 mA	-	750	mV
		I <sub>F</sub> = 50 mA	-	840	mV
		I <sub>F</sub> = 100 mA	-	900	mV
		I <sub>F</sub> = 200 mA	-	1.0	V
		I <sub>F</sub> = 400 mA	-	1.25	V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 90 V	-	100	nA
		V <sub>R</sub> = 90 V, T <sub>A</sub> = 150°C	-	100	µA
C <sub>T</sub>	Total Capacitance	V <sub>R</sub> = 0, f = 1.0 MHz	-	35	pF
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = I <sub>R</sub> = 10 mA, I <sub>RR</sub> = 1.0 mA, R <sub>L</sub> = 100 Ω	-	50	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



**SOT-23**  
**CASE 318BM**  
**ISSUE A**

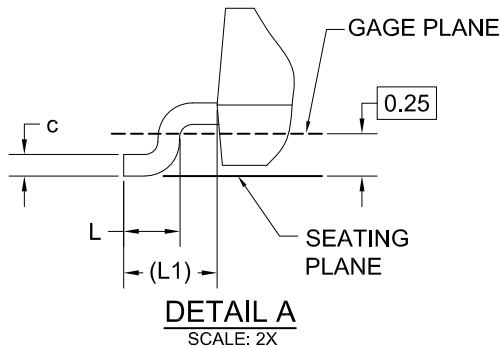
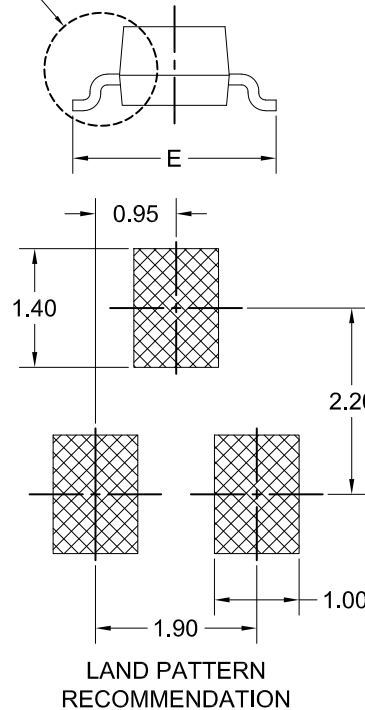
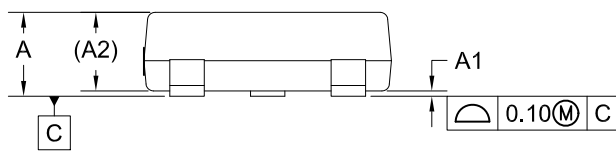
DATE 01 SEP 2021



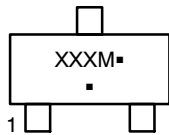
NOTES: UNLESS OTHERWISE SPECIFIED

- A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 2009.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.20
A1	0.00	0.05	0.10
A2	0.93 REF		
b	0.37	0.44	0.60
c	0.08	0.15	0.23
D	2.72	2.92	3.12
E	2.10	2.40	2.70
E1	1.15	1.30	1.50
e	0.95 BSC		
e1	1.90 BSC		
L	0.20	---	---
L1	0.55 REF		
z	0.29 REF		



**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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